

MICRO SD Module board

MB1256

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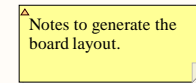
Sheet 2: Top

Legend

General comment such as function title, configuration, ...

Text to be added to silkscreen.

Warning text.



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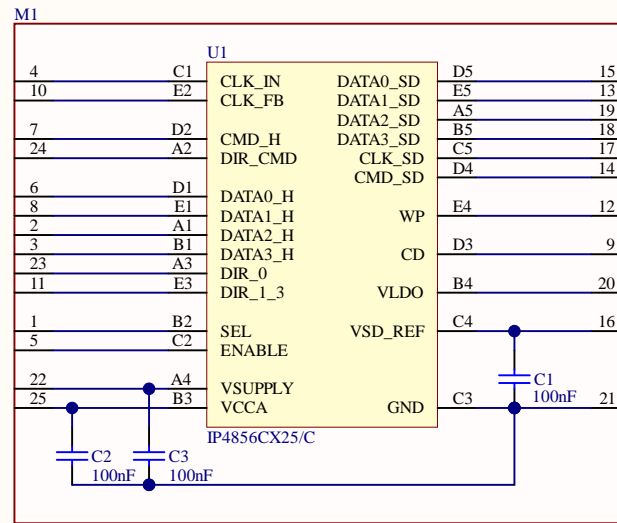
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Title: Project overview		
Project: MICRO SD Module board		
Variant: [No Variations]		
Revision: A-01	Reference: MB1256	
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MICRO SD 3.0 Card



WLCSP module board

